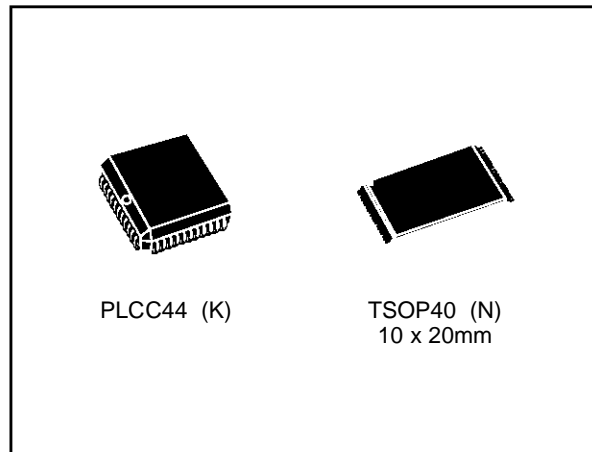


2 Megabit (128K x16) OTP EPROM

PRODUCT PREVIEW

- FAST ACCESS TIME: 55ns
- LOW POWER "CMOS" CONSUMPTION:
 - Active Current 50mA
 - Standby Current 100µA
- PROGRAMMING VOLTAGE: 12.75V
- ELECTRONIC SIGNATURE for AUTOMATED PROGRAMMING
- PROGRAMMING TIME of AROUND 12 sec. (PRESTO II ALGORITHM)



DESCRIPTION

The M27C202 is a high speed 2 Megabit One Time Programmable EPROM, organised as 131,072 by 16 bits. It is ideally suited for microprocessor systems requiring large programs, in the application where the contents is stable and needs to be programmed only one time.

The M27C202 is offered in Plastic Leaded Chip Carrier and Plastic Thin Small Outline packages.

Figure 1. Logic Diagram

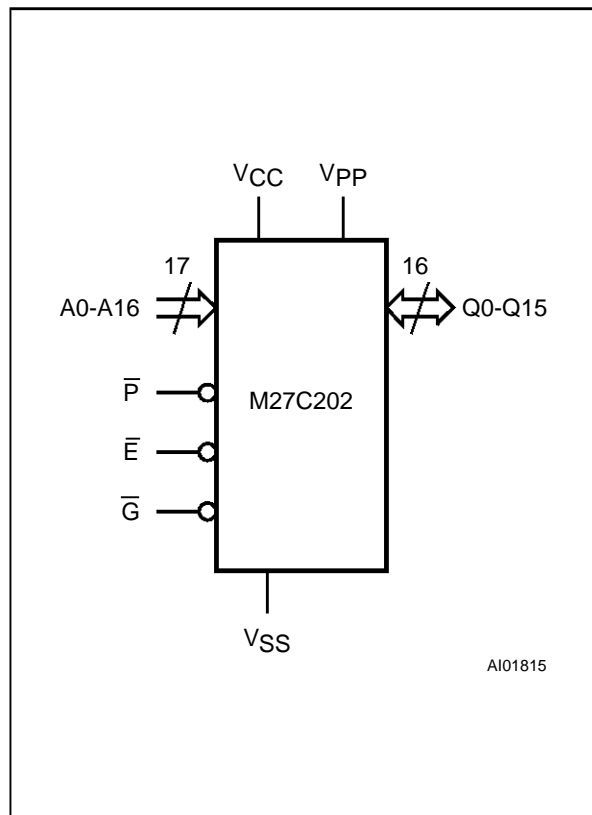


Table 1. Signal Names

A0 - A16	Address Inputs
Q0 - Q15	Data Outputs
\bar{E}	Chip Enable
\bar{G}	Output Enable
\bar{P}	Program
V _{PP}	Program Supply
V _{CC}	Supply Voltage
V _{SS}	Ground

Figure 2A. LCC Pin Connections

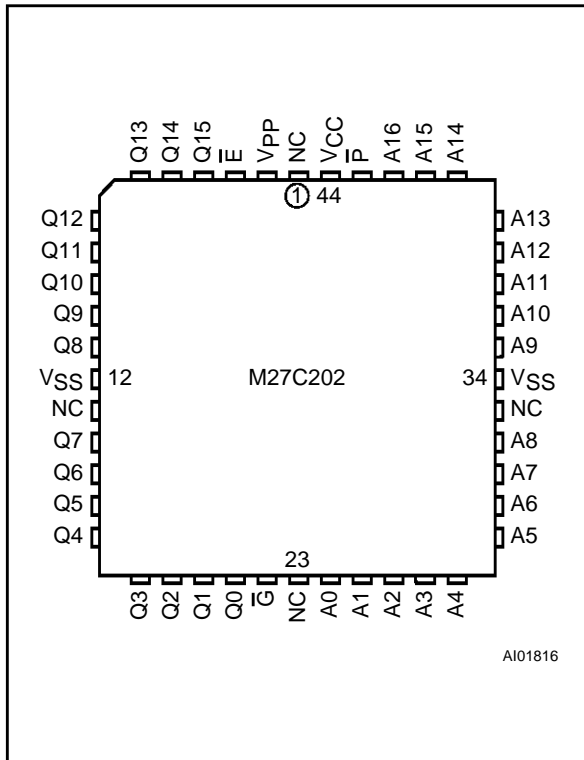
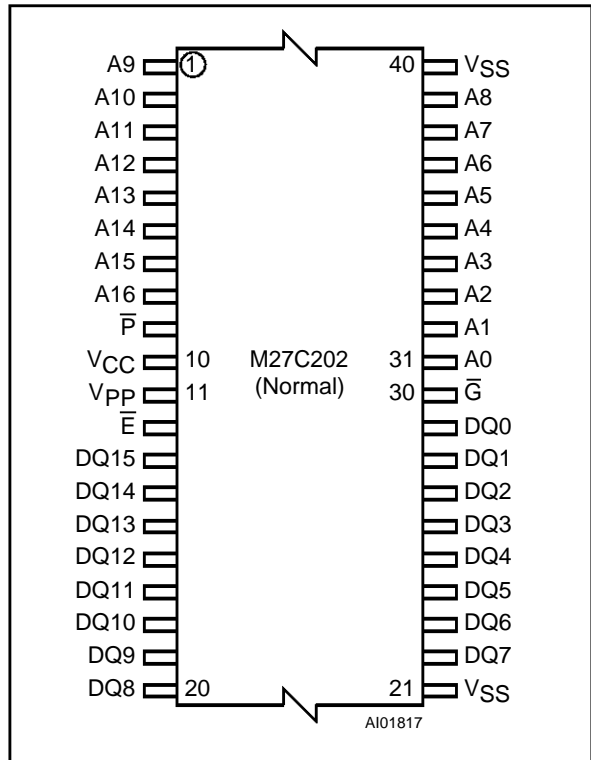


Figure 2B. TSOP Pin Connections



Warning: NC = Not Connected.

Table 2. Absolute Maximum Ratings ⁽¹⁾

Symbol	Parameter	Value	Unit
T _A	Ambient Operating Temperature	-40 to 125	°C
T _{BIAS}	Temperature Under Bias	-50 to 125	°C
T _{STG}	Storage Temperature	-65 to 150	°C
V _{IO (2)}	Input or Output Voltages (except A9)	-2 to 7	V
V _{CC}	Supply Voltage	-2 to 7	V
V _{A9 (2)}	A9 Voltage	-2 to 13.5	V
V _{PP}	Program Supply Voltage	-2 to 14	V

Notes: 1. Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the SGS-THOMSON SURE Program and other relevant quality documents.
 2. Minimum DC voltage on Input or Output is -0.5V with possible undershoot to -2.0V for a period less than 20ns. Maximum DC voltage on Output is V_{CC} +0.5V with possible overshoot to V_{CC} +2V for a period less than 20ns.

Table 3. Operating Modes

Mode	\bar{E}	\bar{G}	\bar{P}	A9	V _{PP}	Q0 - Q15
Read	V _{IL}	V _{IL}	V _{IH}	X	V _{CC} or V _{SS}	Data Output
Output Disable	V _{IL}	V _{IH}	X	X	V _{CC} or V _{SS}	Hi-Z
Program	V _{IL}	X	V _{IL} Pulse	X	V _{PP}	Data Input
Verify	V _{IL}	V _{IL}	V _{IH}	X	V _{PP}	Data Output
Program Inhibit	V _{IH}	X	X	X	V _{PP}	Hi-Z
Standby	V _{IH}	X	X	X	V _{CC} or V _{SS}	Hi-Z
Electronic Signature	V _{IL}	V _{IL}	V _{IH}	V _{ID}	V _{CC}	Codes

Note: X = V_{IH} or V_{IL}, V_{ID} = 12V ±0.5V

Table 4. Electronic Signature

Identifier	A0	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0	Hex Data
Manufacturer's Code	V _{IL}	0	0	1	0	0	0	0	0	20h
Device Code	V _{IH}	0	0	0	1	1	1	0	0	1Ch

DEVICE OPERATION

The modes of operations of the M27C202 are listed in the Operating Modes table. A single power supply is required in the read mode. All inputs are TTL levels except for V_{pp} and 12V on A9 for Electronic Signature.

Read Mode

The M27C202 has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (\bar{E}) is the power control and should be used for device selection. Output Enable (\bar{G}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that the addresses are stable, the address access time (t_{AVQV}) is equal to the delay from \bar{E} to output (t_{ELQV}). Data is available at the output after a delay of t_{OE} from the falling edge of \bar{G} , assuming that \bar{E} has been low and the addresses have been stable for at least t_{AVQV}-t_{GLQV}.

Standby Mode

The M27C202 has a standby mode which reduces the active current from 50mA to 100µA.

The M27C202 is placed in the standby mode by applying a TTL high signal to the \bar{E} input. When in the standby mode, the outputs are in a high impedance state, independent of the \bar{G} input.

Two Line Output Control

Because OTP EPROMs are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

- the lowest possible memory power dissipation,
- complete assurance that output bus contention will not occur.

For the most efficient use of these two control lines, \bar{E} should be decoded and used as the primary device selecting function, while \bar{G} should be made a common connection to all devices in the array and connected to the \overline{READ} line from the system control bus. This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

Table 5. AC Measurement Conditions

	High Speed	Standard
Input Rise and Fall Times	≤ 10ns	≤ 20ns
Input Pulse Voltages	0 to 3V	0.45V to 2.4V
Input and Output Timing Ref. Voltages	1.5V	0.8V and 2V

Figure 3. AC Testing Input Output Waveform

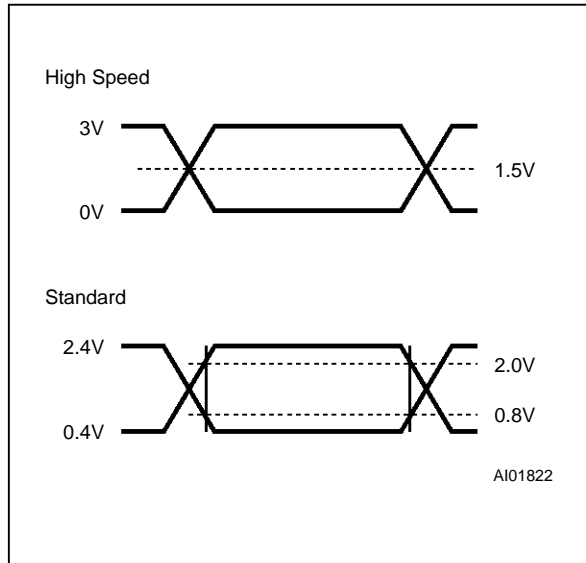


Figure 4. AC Testing Load Circuit

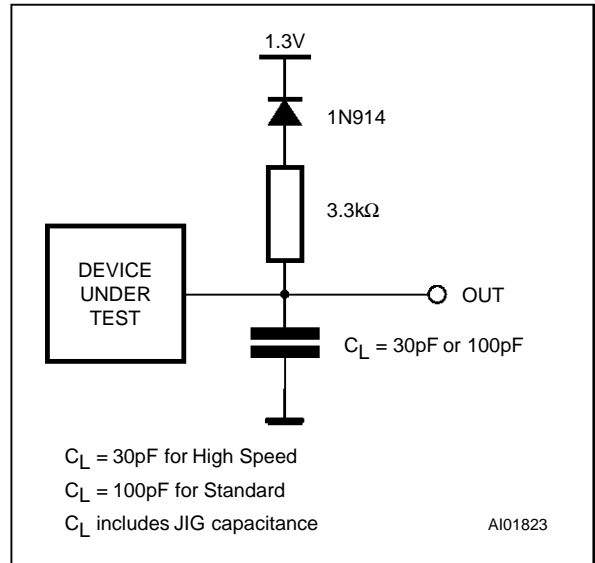


Table 6. Capacitance⁽¹⁾ (T_A = 25 °C, f = 1 MHz)

Symbol	Parameter	Test Condition	Min	Max	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V		6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

Figure 5. Read Mode AC Waveforms

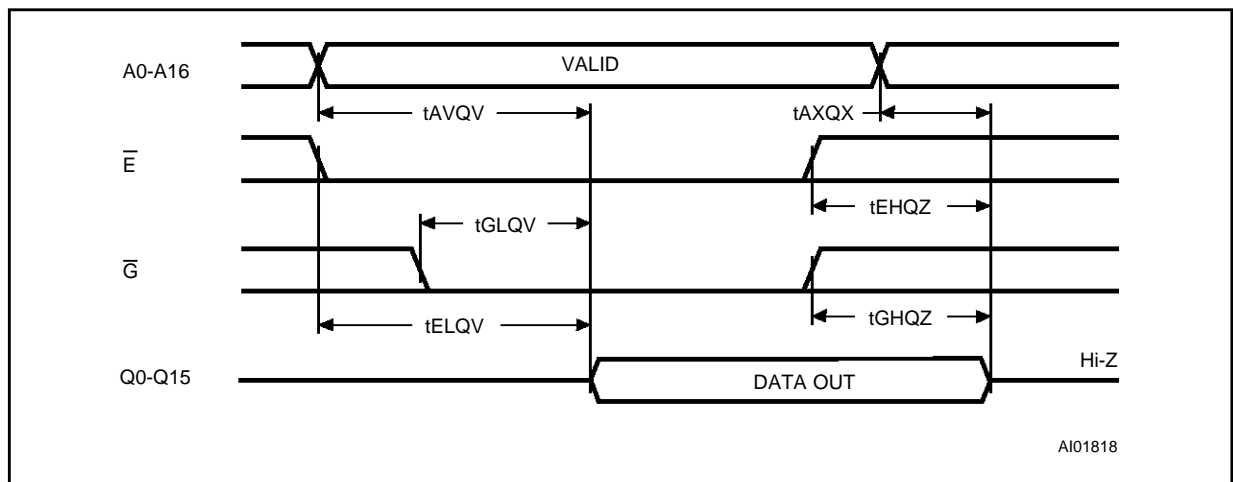


Table 7. Read Mode DC Characteristics ⁽¹⁾(T_A = 0 to 70 °C, –40 to 85 °C or –40 to 125 °C; V_{CC} = 5V ± 10%; V_{PP} = V_{CC})

Symbol	Parameter	Test Condition	Min	Max	Unit
I _{LI}	Input Leakage Current	0V ≤ V _{IN} ≤ V _{CC}		±10	μA
I _{LO}	Output Leakage Current	0V ≤ V _{OUT} ≤ V _{CC}		±10	μA
I _{CC}	Supply Current	$\bar{E} = V_{IL}, \bar{G} = V_{IL},$ I _{OUT} = 0mA, f = 5MHz		50	mA
I _{CC1}	Supply Current (Standby) TTL	$\bar{E} = V_{IH}$		1	mA
I _{CC2}	Supply Current (Standby) CMOS	$\bar{E} > V_{CC} - 0.2V$		100	μA
I _{PP}	Program Current	V _{PP} = V _{CC}		100	μA
V _{IL}	Input Low Voltage		–0.3	0.8	V
V _{IH} ⁽²⁾	Input High Voltage		2	V _{CC} + 1	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1mA		0.4	V
V _{OH}	Output High Voltage TTL	I _{OH} = –400μA	2.4		V
	Output High Voltage CMOS	I _{OH} = –100μA	V _{CC} – 0.7V		V

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP}.
2. Maximum DC voltage on Output is V_{CC} + 0.5V.

System Considerations

The power switching characteristics of Advanced OTP EPROMs require careful decoupling of the devices. The supply current, I_{CC}, has three segments that are of interest to the system designer: the standby current level, the active current level, and transient current peaks that are produced by the falling and rising edges of \bar{E} . The magnitude of transient current peaks is dependent on the capacitive and inductive loading of the device at the output. The associated transient voltage peaks can be suppressed by complying with the two line output control and by properly selected decoupling capacitors. It is recommended that a 0.1μF ceramic capacitor be used on every device between V_{CC} and V_{SS}. This should be a high frequency capacitor of low inherent inductance and should be placed as close to the device as possible. In addition,

a 4.7μF bulk electrolytic capacitor should be used between V_{CC} and V_{SS} for every eight devices. The bulk capacitor should be located near the power supply connection point. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of PCB traces.

Programming

When delivered, all bits of the M27C202 are in the "1" state. Data is introduced by selectively programming "0"s into the desired bit locations. Although only "0"s will be programmed, both "1"s and "0"s can be present in the data word. The M27C202 is in the programming mode when V_{PP} input is at 12.75V, and \bar{E} and \bar{P} are at TTL-low. The data to be programmed is applied to 16 bits in parallel, to the data output pins. The levels required for the address and data inputs are TTL. V_{CC} is specified to be 6.25V ± 0.25V.

Table 8A. Read Mode AC Characteristics ⁽¹⁾

(T_A = 0 to 70 °C, -40 to 85 °C or -40 to 125 °C; V_{CC} = 5V ± 10%; V_{PP} = V_{CC})

Symbol	Alt	Parameter	Test Condition	M27C202								Unit
				-55 ⁽³⁾		-70		-80		-90		
				Min	Max	Min	Max	Min	Max	Min	Max	
t _{AVQV}	t _{ACC}	Address Valid to Output Valid	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$		55		70		80		90	ns
t _{ELQV}	t _{CE}	Chip Enable Low to Output Valid	$\bar{G} = V_{IL}$		55		70		80		90	ns
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid	$\bar{E} = V_{IL}$		30		35		40		45	ns
t _{EHQZ} ⁽²⁾	t _{DF}	Chip Enable High to Output Hi-Z	$\bar{G} = V_{IL}$	0	30	0	30	0	30	0	30	ns
t _{GHQZ} ⁽²⁾	t _{DF}	Output Enable High to Output Hi-Z	$\bar{E} = V_{IL}$	0	30	0	30	0	30	0	30	ns
t _{AXQX}	t _{OH}	Address Transition to Output Transition	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$	0		0		0		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP}.
 2. Sampled only, not 100% tested.
 3. See High Speed AC Measurement condition for 55ns speed.

Table 8B. Read Mode AC Characteristics ⁽¹⁾

(T_A = 0 to 70 °C, -40 to 85 °C or -40 to 125 °C; V_{CC} = 5V ± 10%; V_{PP} = V_{CC})

Symbol	Alt	Parameter	Test Condition	M27C202								Unit
				-10		-12		-15		-20		
				Min	Max	Min	Max	Min	Max	Min	Max	
t _{AVQV}	t _{ACC}	Address Valid to Output Valid	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$		100		120		150		200	ns
t _{ELQV}	t _{CE}	Chip Enable Low to Output Valid	$\bar{G} = V_{IL}$		100		120		150		200	ns
t _{GLQV}	t _{OE}	Output Enable Low to Output Valid	$\bar{E} = V_{IL}$		50		60		60		70	ns
t _{EHQZ} ⁽²⁾	t _{DF}	Chip Enable High to Output Hi-Z	$\bar{G} = V_{IL}$	0	30	0	40	0	50	0	60	ns
t _{GHQZ} ⁽²⁾	t _{DF}	Output Enable High to Output Hi-Z	$\bar{E} = V_{IL}$	0	30	0	40	0	50	0	60	ns
t _{AXQX}	t _{OH}	Address Transition to Output Transition	$\bar{E} = V_{IL}, \bar{G} = V_{IL}$	0		0		0		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP}.
 2. Sampled only, not 100% tested.

Table 9. Programming Mode DC Characteristics ⁽¹⁾
 ($T_A = 25\text{ }^\circ\text{C}$; $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$; $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$)

Symbol	Parameter	Test Condition	Min	Max	Unit
I_{LI}	Input Leakage Current	$0 \leq V_{IN} \leq V_{IH}$		± 10	μA
I_{CC}	Supply Current			50	mA
I_{PP}	Program Current	$\bar{E} = V_{IL}$		50	mA
V_{IL}	Input Low Voltage		-0.3	0.8	V
V_{IH}	Input High Voltage		2	$V_{CC} + 0.5$	V
V_{OL}	Output Low Voltage	$I_{OL} = 2.1\text{mA}$		0.4	V
V_{OH}	Output High Voltage TTL	$I_{OH} = -400\mu\text{A}$	2.4		V
V_{ID}	A9 Voltage		11.5	12.5	V

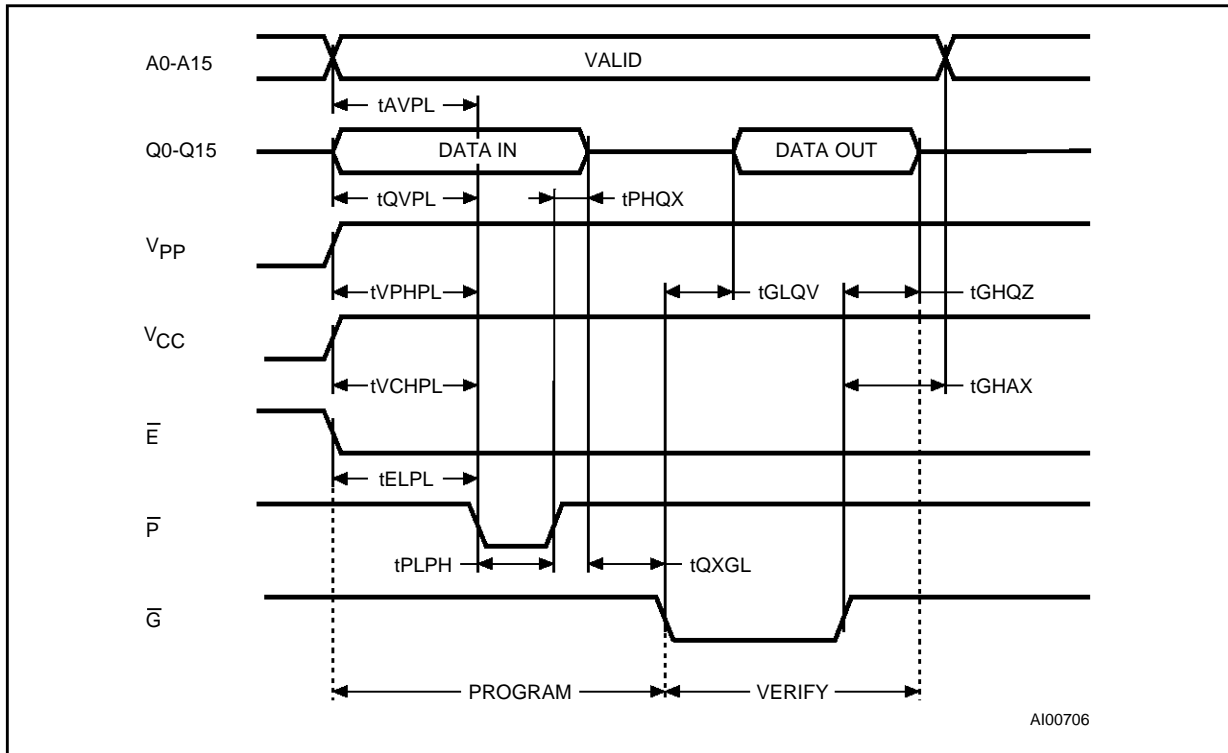
Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP} .

Table 10. Programming Mode AC Characteristics ⁽¹⁾
 ($T_A = 25\text{ }^\circ\text{C}$; $V_{CC} = 6.25\text{V} \pm 0.25\text{V}$; $V_{PP} = 12.75\text{V} \pm 0.25\text{V}$)

Symbol	Alt	Parameter	Test Condition	Min	Max	Unit
t_{AVPL}	t_{AS}	Address Valid to Program Low		2		μs
t_{QVPL}	t_{DS}	Input Valid to Program Low		2		μs
t_{VPHPL}	t_{VPS}	V_{PP} High to Program Low		2		μs
t_{VCHPL}	t_{VCS}	V_{CC} High to Program Low		2		μs
t_{ELPL}	t_{CES}	Chip Enable Low to Program Low		2		μs
t_{PLPH}	t_{PW}	Program Pulse Width		95	105	μs
t_{PHQX}	t_{DH}	Program High to Input Transition		2		μs
t_{QXGL}	t_{OES}	Input Transition to Output Enable Low		2		μs
t_{GLQV}	t_{OE}	Output Enable Low to Output Valid			100	ns
$t_{GHQZ}^{(2)}$	t_{DFP}	Output Enable High to Output Hi-Z		0	130	ns
t_{GHAX}	t_{AH}	Output Enable High to Address Transition		0		ns

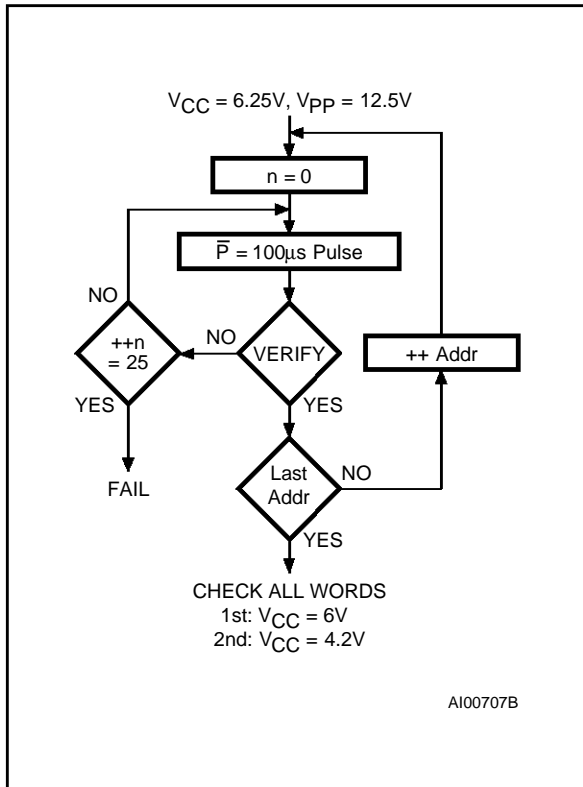
Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously with or after V_{PP} .
 2. Sampled only, not 100% tested.

Figure 6. Programming and Verify Modes AC Waveforms



AI00706

Figure 7. Programming Flowchart



AI00707B

PRESTO II Programming Algorithm

PRESTO II Programming Algorithm allows programming of the whole array with a guaranteed margin, in a typical time of 13 seconds. Programming with PRESTO II consists of applying a sequence of 100 µs program pulses to each word until a correct verify occurs (see Figure 7). During programming and verify operation, a MARGIN MODE circuit is automatically activated in order to guarantee that each cell is programmed with enough margin. No overprogram pulse is applied since the verify in MARGIN MODE provides necessary margin to each programmed cell.

Program Inhibit

Programming of multiple M27C202s in parallel with different data is also easily accomplished. Except for \bar{E} , all like inputs including \bar{G} of the parallel M27C202 may be common. A TTL low level pulse applied to a M27C202's \bar{E} input, with \bar{P} low and V_{PP} at 12.75V, will program that M27C202. A high level \bar{E} input inhibits the other M27C202s from being programmed.

Program Verify

A verify (read) should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with \bar{E} and \bar{G} at V_{IL}, \bar{P} at V_{IH}, V_{PP} at 12.75V and V_{CC} at 6.25V.

On-Board Programming

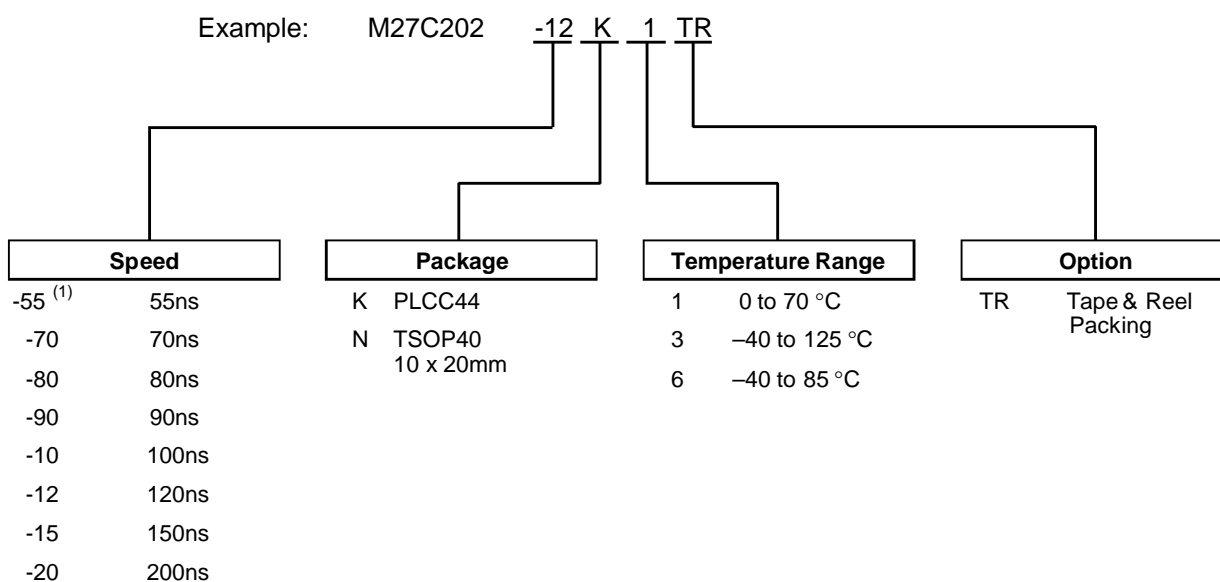
The M27C202 can be directly programmed in the application circuit. See the relevant Application Note AN620.

Electronic Signature

The Electronic Signature (ES) mode allows the reading out of a binary code from an OTP EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment to automatically match the device to be programmed with its corresponding programming algorithm. The ES mode is functional in the $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ ambient temperature range that is required

when programming the M27C202. To activate the ES mode, the programming equipment must force 11.5V to 12.5V on address line A9 of the M27C202 with $V_{PP} = V_{CC} = 5\text{V}$. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from V_{IL} to V_{IH} . All other address lines must be held at V_{IL} during Electronic Signature mode. Byte 0 ($A0=V_{IL}$) represents the manufacturer code and byte 1 ($A0=V_{IH}$) the device identifier code. For the SGS-THOMSON M27C202, these two identifier bytes are given in Table 4 and can be read-out on outputs Q0 to Q7.

ORDERING INFORMATION SCHEME



Note: 1. High Speed, see AC Characteristics section for further information.

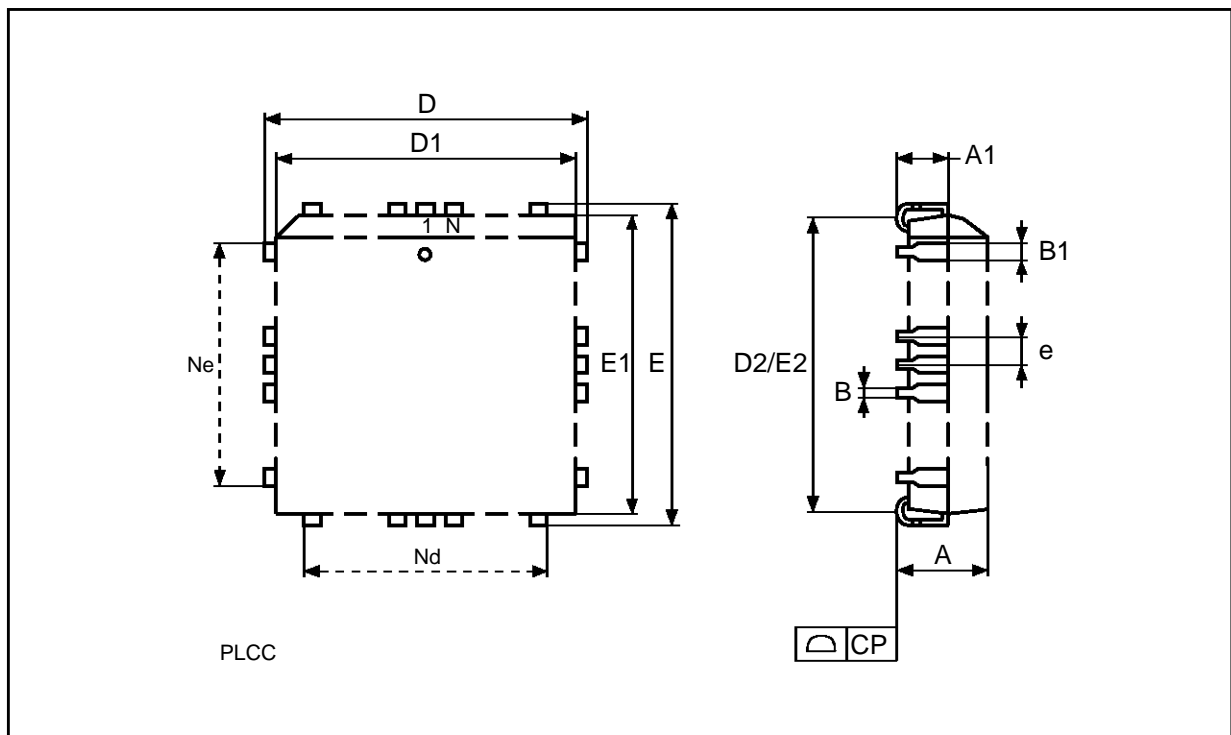
For a list of available options (Speed, V_{CC} Tolerance, Package, etc...) refer to the current Memory Shortform catalogue.

For further information on any aspect of this device, please contact the SGS-THOMSON Sales Office nearest to you.

PLCC44 - 44 lead Plastic Leaded Chip Carrier, square

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A		4.20	4.70		0.165	0.185
A1		2.29	3.04		0.090	0.120
B		0.33	0.53		0.013	0.021
B1		0.66	0.81		0.026	0.032
D		17.40	17.65		0.685	0.695
D1		16.51	16.66		0.650	0.656
D2		14.99	16.00		0.590	0.630
E		17.40	17.65		0.685	0.695
E1		16.51	16.66		0.650	0.656
E2		14.99	16.00		0.590	0.630
e	1.27	-	-	0.050	-	-
N	44			44		
CP			0.10			0.004

PLCC44

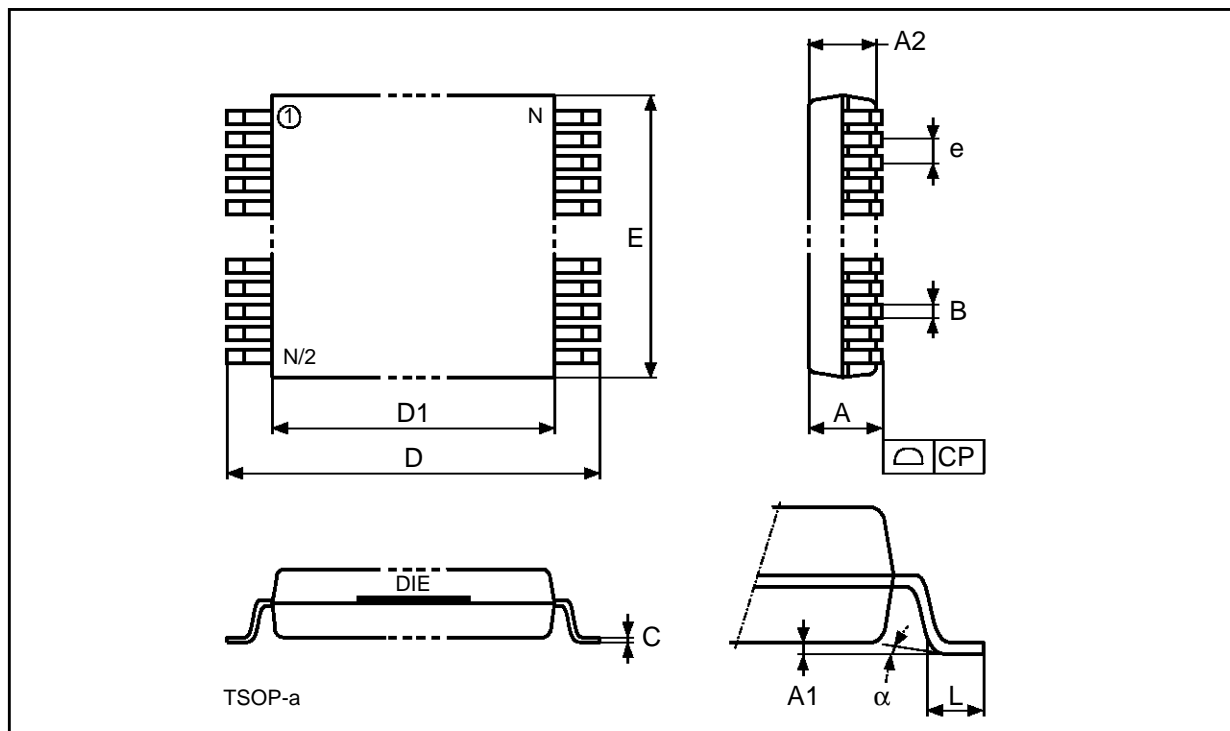


Drawing is not to scale

TSOP40 - 40 lead Plastic Thin Small Outline, 10 x 20mm

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			1.20			0.047
A1		0.05	0.15		0.002	0.006
A2		0.95	1.05		0.037	0.041
B		0.17	0.27		0.007	0.011
C		0.10	0.21		0.004	0.008
D		19.80	20.20		0.780	0.795
D1		18.30	18.50		0.720	0.728
E		9.90	10.10		0.390	0.398
e	0.50	–	–	0.020	–	–
L		0.50	0.70		0.020	0.028
α		0°	5°		0°	5°
N	40			40		
CP			0.10			0.004

TSOP40



Drawing is not to scale

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